

L Number	Hits	Search Text	DB	Time stamp
11	149	(711/5.ccls. and module) and (arrang\$4 layout)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/14 14:14
12	349	711/5.ccls. and module	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/14 14:14
13	57	((711/\$.ccls. and module) and row) and ((ic chip) near3 arrang\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/14 14:15
14	3	(memory and module and ((IC chip) with arrang\$5)) and (bilateral near2 symmetr\$7)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/14 14:15
15	128	module and (((IC chip) with arrang\$5) with symmetr\$7)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/14 14:24
16	84	((memory and module and packag\$3) and (first adj row) and (second adj row)) and lateral\$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/14 14:16
17	4	(module and (((IC chip) with arrang\$5) with symmetr\$7)) and (second adj2 (buffer register))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/14 14:24
24	1	(711/5.ccls. and module) and ((first adj2 (buffer register)) with (first adj2 row)) and ((second adj2 (buffer register)) with (second adj2 row))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/14 15:00
25	2579	(memory near2 module) and pack\$4 and (pcb (printed near3 circuit near3 board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/14 15:00
26	4	((memory near2 module) and pack\$4 and (pcb (printed near3 circuit near3 board))) and ((first adj2 (buffer register)) with (first adj2 row)) and ((second adj2 (buffer register)) with (second adj2 row))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/14 15:01
27	8	((memory near2 module) and pack\$4 and (pcb (printed near3 circuit near3 board))) and ((first adj2 (buffer register)) with row) and ((second adj2 (buffer register)) with row)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/14 15:02
28	13	((memory near2 module) and pack\$4 and (pcb (printed near3 circuit near3 board))) and ((first adj2 (buffer register)) with (chip Ic (integrated adj circuit))) and ((second adj2 (buffer register)) with (chip Ic (integrated adj circuit)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/14 15:54

29	26	US-4280176-\$.DID. OR US-4679167-\$.DID. OR US-0522636-\$.DID. OR US-5303123-\$.DID. OR US-5428762-\$.DID. OR US-5541448-\$.DID. OR US-5572691-\$.DID. OR US-5631807-\$.DID. OR US-5652861-\$.DID. OR US-5737192-\$.DID. OR US-5835932-\$.DID. OR US-5953738-\$.DID. OR US-6021048-\$.DID. OR US-0657538-\$.DID. OR US-622273B1-\$.DID. OR US-635353B1-\$.DID. OR US-65325B1-\$.DID.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/14 15:53
30	38	US-5012389-\$.DID. OR US-5164916-\$.DID. OR US-5191404-\$.DID. OR US-5383148-\$.DID. OR US-5412538-\$.DID. OR US-5465229-\$.DID. OR US-5495435-\$.DID. OR US-5513135-\$.DID. OR US-5532954-\$.DID. OR US-5642323-\$.DID. OR US-5652462-\$.DID. OR US-5661339-\$.DID. OR US-5691946-\$.DID. OR US-0571281-\$.DID. OR US-5743408-\$.DID. OR US-5847986-\$.DID. OR US-5867448-\$.DID. OR US-5973951-\$.DID. OR US-6072744-\$.DID. OR US-6097619-\$.DID. OR US-6151235-\$.DID. OR US-618100B1-\$.DID. OR US-621571B1-\$.DID. OR US-622273B1-\$.DID. OR US-635353B1-\$.DID. OR US-650216B1-\$.DID. OR US-654589B1-\$.DID.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/14 15:53
32	64	(US-4280176-\$.DID. OR US-4679167-\$.DID. OR US-0522636-\$.DID. OR US-5303123-\$.DID. OR US-5428762-\$.DID. OR US-5541448-\$.DID. OR US-5572691-\$.DID. OR US-5631807-\$.DID. OR US-5652861-\$.DID. OR US-5737192-\$.DID. OR US-5835932-\$.DID. OR US-5953738-\$.DID. OR US-6021048-\$.DID. OR US-0657538-\$.DID. OR US-622273B1-\$.DID. OR US-635353B1-\$.DID. OR US-65325B1-\$.DID.) or (US-5012389-\$.DID. OR US-5164916-\$.DID. OR US-5191404-\$.DID. OR US-5383148-\$.DID. OR US-5412538-\$.DID. OR US-5465229-\$.DID. OR US-5495435-\$.DID. OR US-5513135-\$.DID. OR US-5532954-\$.DID. OR US-5642323-\$.DID. OR US-5652462-\$.DID. OR US-5661339-\$.DID. OR US-5691946-\$.DID. OR US-0571281-\$.DID. OR US-5743408-\$.DID. OR US-5847986-\$.DID. OR US-5867448-\$.DID. OR US-5973951-\$.DID. OR US-6072744-\$.DID. OR US-6097619-\$.DID. OR US-6151235-\$.DID. OR US-618100B1-\$.DID. OR US-621571B1-\$.DID. OR US-622273B1-\$.DID. OR US-635353B1-\$.DID. OR US-650216B1-\$.DID. OR US-654589B1-\$.DID.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/14 15:54
35	2433	((chip IC (integrated adj circuit)) with arrang\$3 with opposite	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/14 16:57
38	172	((chip IC (integrated adj circuit)) with arrang\$3 with opposite) and module and memory	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/14 16:57
39	2261	((chip IC (integrated adj circuit)) with arrang\$3 with opposite) not (((chip IC (integrated adj circuit)) with arrang\$3 with opposite) and module and memory)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/14 16:58
40	172	((chip IC (integrated adj circuit)) with arrang\$3 with opposite) not (((chip IC (integrated adj circuit)) with arrang\$3 with opposite) not (((chip IC (integrated adj circuit)) with arrang\$3 with opposite) and module and memory))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/14 16:58